

# PROCIRC 9972

## HOT AIR LEVELING FLUX

### INTRODUCTION

Procirc 9972 is a heat stable organic flux used in vertical hot air levelling.

It is water soluble, non-foaming and is easily removed by rinsing the printed circuit boards in water.

Procirc 9972 shows very little carbonisation.

### BENEFITS

Non-drying, therefore blanketing the molten solder to prevent re-oxidation as well as preventing solder balls sticking to the solder mask or laminate.

First time coverage of very difficult SMD pads.

High SIR-values better than  $10^{10}$  Ohm can be obtained in vertical HAL.

Complete edge coverage.

Low copper dissolution.

Biodegradable.

### SOLUTION CHARACTERISTICS

Specific gravity (25°C)	1.1g/cm <sup>3</sup>
Viscosity (25°C)	115cps
Flash point (COC)	300°C

### EQUIPMENT

Can be used in dip or roller applications.

### INSTALLATION

It is essential that the tanks to be used for Procirc 9972 HAL Flux are thoroughly cleaned before any chemistry is introduced.

Contact PMD (UK) Limited Technical Department for appropriate procedure.

## **PROCESS SEQUENCE**

1. Microetch in Procirc 921,923 or SP263 Microetch.
2. Rinse.
3. Dry (Preferable).
4. Procirc 9972 Hot Air Levelling Flux application (roller or dip).
5. Solder level.
6. Wash off.
7. Dry.

## **MAINTENANCE AND CONTROL**

Under optimum processing conditions it is not necessary to carry out analytical maintenance and control in order to maintain the performance of this product.

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## **DISPOSAL**

Dispose of in accordance with Local Authority requirements.

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## **PRODUCT FAMILIES**

The following products are referred to in this Data Sheet.

<u>Product Name</u>	<u>Product Number</u>
Procirc 9972 Hot Air Levelling Flux	997024
Procirc 921 Microetch	923001
Procirc 923 Mircoetch	927001
Procirc SP263 Microetch	923003

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